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(54) Title: DI METAL TRANSACTION DEVICES AND PROCESSES FOR THE MANUFACTURE THEREOF

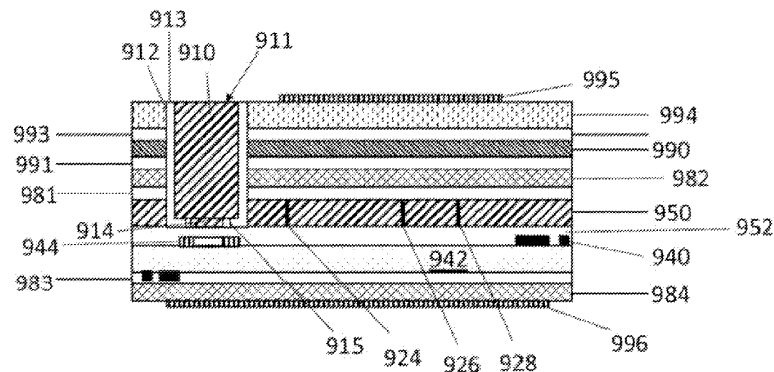


FIG. 9C

(57) Abstract: A transaction device includes a metal layer with one or more discontinuities in the metal layer. Each discontinuity comprises a gap in the metal layer extending from the front surface to the back surface, including at least one discontinuity that defines a path from the device periphery to the opening. A transponder chip module is disposed in the opening. A booster antenna is in communication with the transponder chip module. The device may include at least one fiber-reinforced epoxy laminate material layer. The transponder chip module and the booster antenna may comprise components in a payment circuit, with the metal layer electrically isolated from the payment circuit. The booster antenna may be formed on or embedded in the fiber-reinforced epoxy laminate material layer. Processes for manufacturing transaction devices including a metal layer with one or more fiber-reinforced epoxy laminate material layers are also disclosed.

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